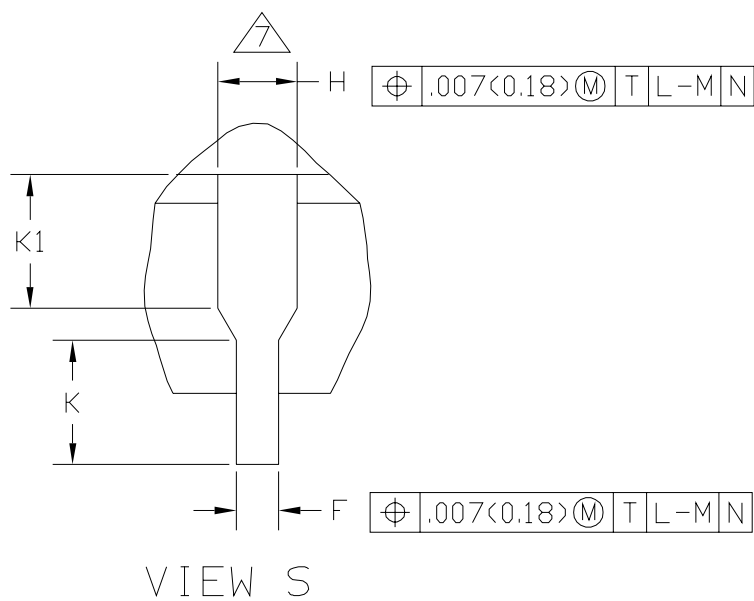
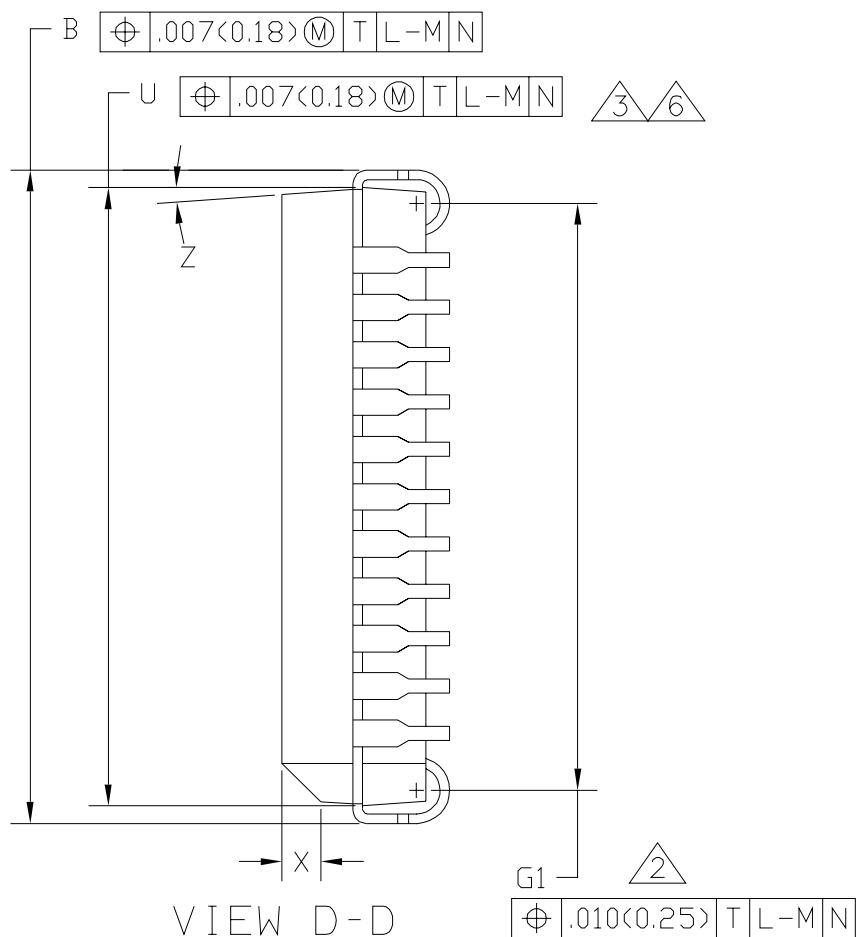




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TITLE: MOS/BI POLAR (44 LEAD) PLASTIC LEADED CHIP CARRIER	DOCUMENT NO: 98ASB42598B		REV: E
	CASE NUMBER: 777-02		24 MAY 2005
	STANDARD: NON-JEDEC		

NOTES:

1. DATUM L, M, AND N DETERMINE WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.

△2. DIMENSION TRUE POSITION TO BE MEASURED AT DATUM T, SEATING PLANE.

△3. DIMENSIONS DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS .010 (0.25) PER SIDE.

4. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

5. CONTROLLING DIMENSION: INCH

△6. THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO .012 (0.30). DIMENSIONS ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.

△7. DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE DIMENSION TO BE GREATER THAN .037 (0.94). THE DAM BAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN .025 (0.635).

DIM	INCH		MILLIMETER		DIM	INCH		MILLIMETER	
	MIN	MAX	MIN	MAX		MIN	MAX	MIN	MAX
A	.685	.695	17.40	17.65	Y	---	.020	---	0.50
B	.685	.695	17.40	17.65	Z	2°	10°	2°	10°
C	.165	.180	4.20	4.57	G1	.610	.630	15.50	16.00
E	.090	.110	2.29	2.79	K1	.040	---	1.02	---
F	.013	.019	0.33	0.48					
G	.050 BSC		1.27 BSC						
H	.026	.032	0.66	0.81					
J	.020	---	0.51	---					
K	.025	---	0.64	---					
R	.650	.656	16.51	16.66					
U	.650	.656	16.51	16.66					
V	.042	.048	1.07	1.21					
W	.042	.048	1.07	1.21					
X	.042	.056	1.07	1.42					

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